

**CLAIMS.**

1. An optoelectronic component based on the surface mount technology, said component comprising

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a electrically conductive material (1),

an opaque plastic material (2), and

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a cavity (5),

wherein the said electrically conductive material (1) serves as a base for the assembly, the said opaque plastic material (2) provides a housing for the whole component, and the said cavity (5) is located within the plastic material where an optoelectronic chip (3) is mounted in.

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2. An optoelectronic component as claimed in claim 1, wherein the cavity (5) is filled with a transparent and translucent resin material.

- 20 3. An optoelectronic component as claimed in claim 1, wherein electrical connection(s) between the chip (3) and the base material is provided with a metallic wire (4).

4. An optoelectronic component as claimed in claim 1, wherein initial base material provides connecting terminals to the external sub-systems such as PCBs.

5. An optoelectronic component as claimed in claim 1, wherein the said base material protrudes from the middle to the bottom (8) and to one of the sidewalls (7).

6. An optoelectronic component as claimed in claim 5, wherein the said base material protrudes outside the plastic package.

7. An optoelectronic component as claimed in claim 1, wherein the said base material protrudes to the two other sides (6) of the plastic package.

8. An optoelectronic component as claimed in claim 1, wherein the side protrusions can be used for electrical connections.

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